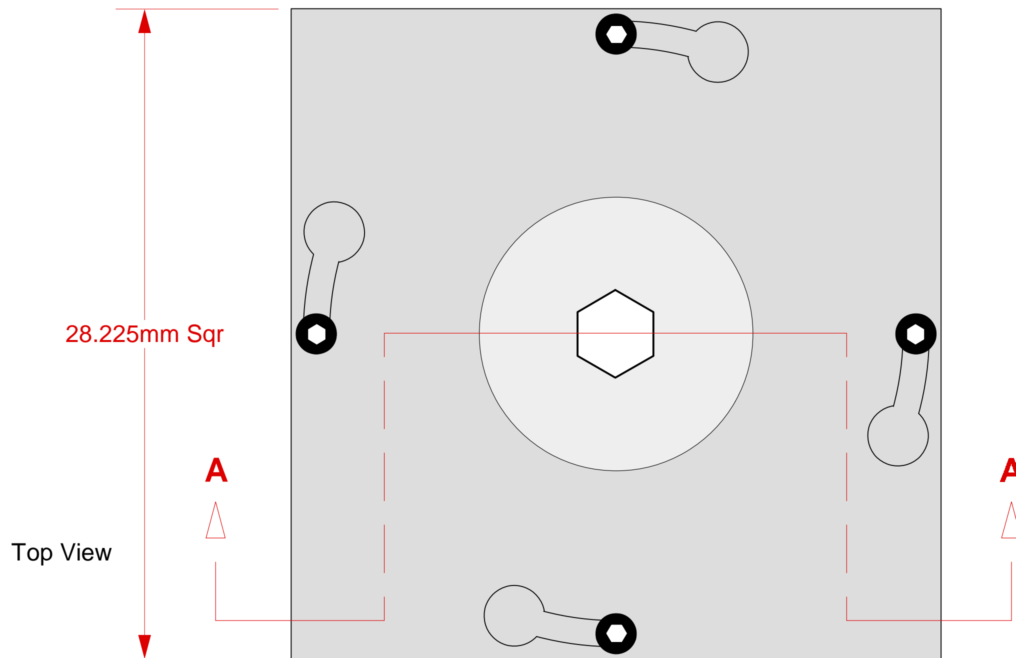
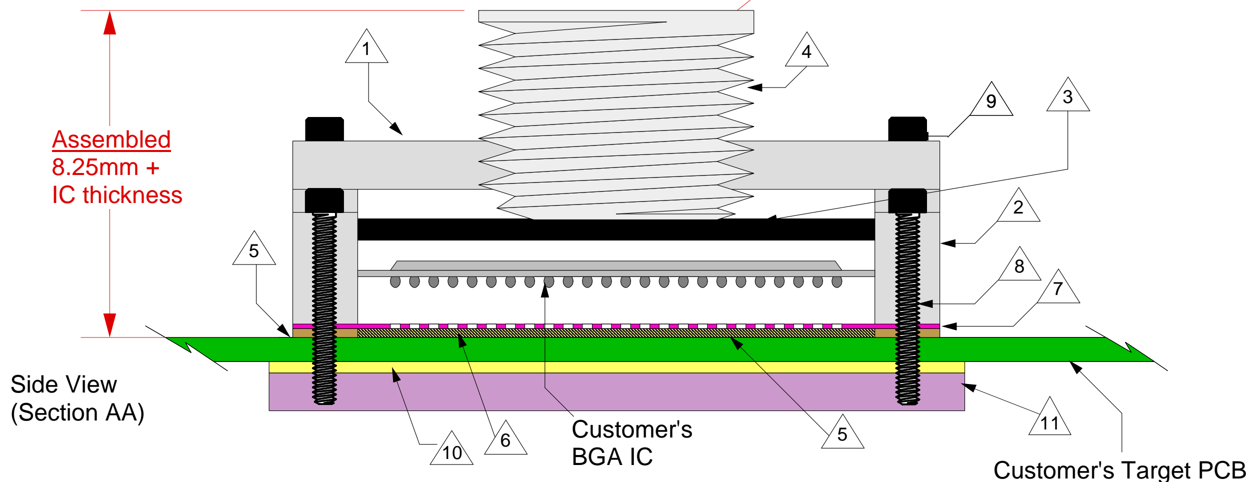
GHz BGA Socket - Direct mount, solderless



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



#	Description
1	Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
2	Socket base: Black anodized Aluminum. Thickness = 5mm.
3	Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
4	Compression screw: Clear anodized Aluminum. Hex socket = 5mm, fin height 5mm
5	Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
6	Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
7	Ball Guide: Kapton polyimide.
8	Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 12.7mm long.
9	Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
10	Insulation Plate: FR4/G10, Thickness = 1.59mm.
11	Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-6266 Drawing	Status:Released	Scale: -	Rev: B
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	File: **SG-BGA-6266** Dwg.mcd	Modified: 8/10/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

*Note: BGA pattern is not symmetrical with respect to the mounting holes. It is offset 0.375mm to the right of center.**

Orientation Mark

2.8375mm*

0.8mm typ.

2.4625mm

2.54mm

Ø 0.85mm±0.025mm (x2)
Alignment Hole

28.225mm±0.125mm sqr.
Socket size

Ø 0.43mm PAD

5.08mm

1.25mm±0.13mm

Ø 1.61mm±0.05mm(x4)
Mounting Hole

25.725mm(x4)

1.25mm±0.13mm

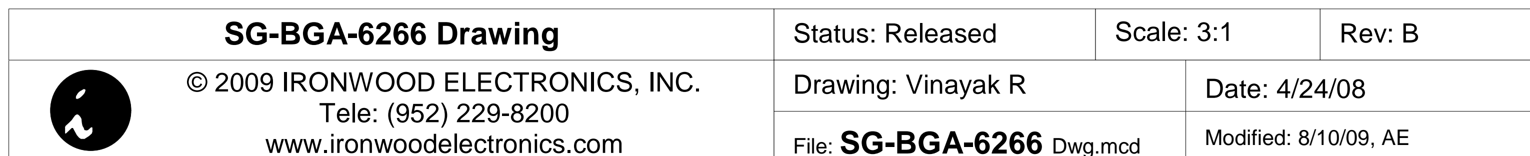
30.725mm sq. backing plate

Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.

Target PCB Recommendations
Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001”] unless stated otherwise.



SG-BGA-6266 Drawing	Status: Released	Scale: 3:1	Rev: B
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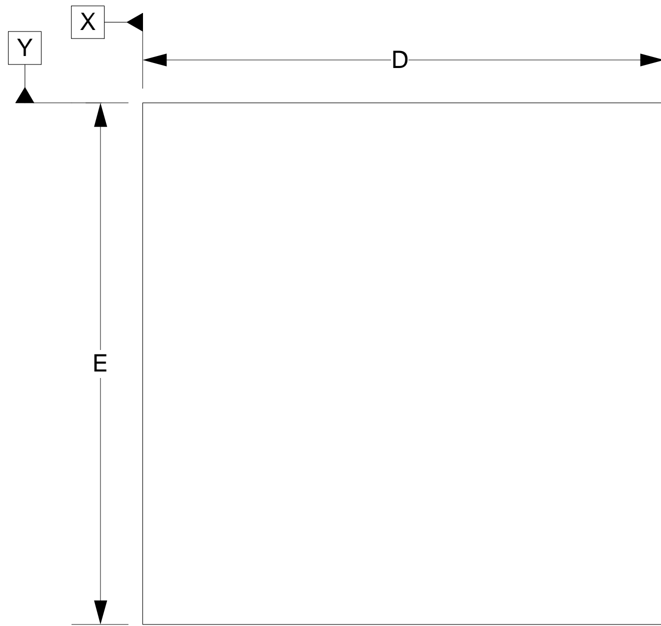
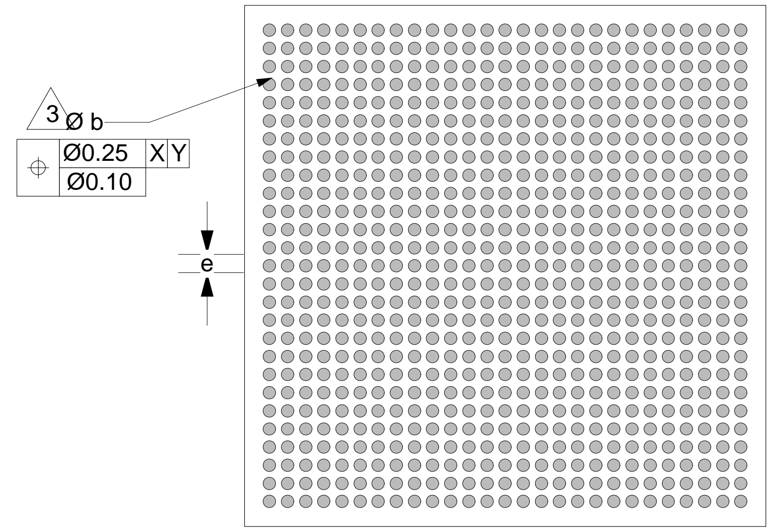
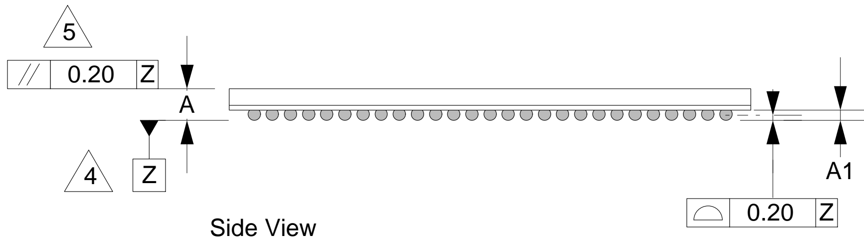
Compatible BGA Spec.



Top View



Bottom View Array:27x27

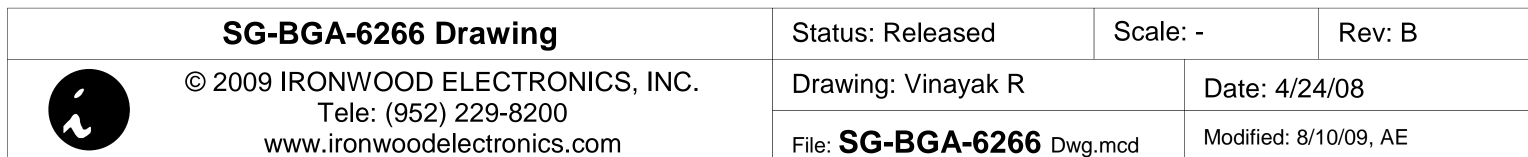


Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.15
A1	0.25	0.35
b		0.50
D	23.0 BSC	
E	23.0 BSC	
e	0.8 BSC	

27x27 array



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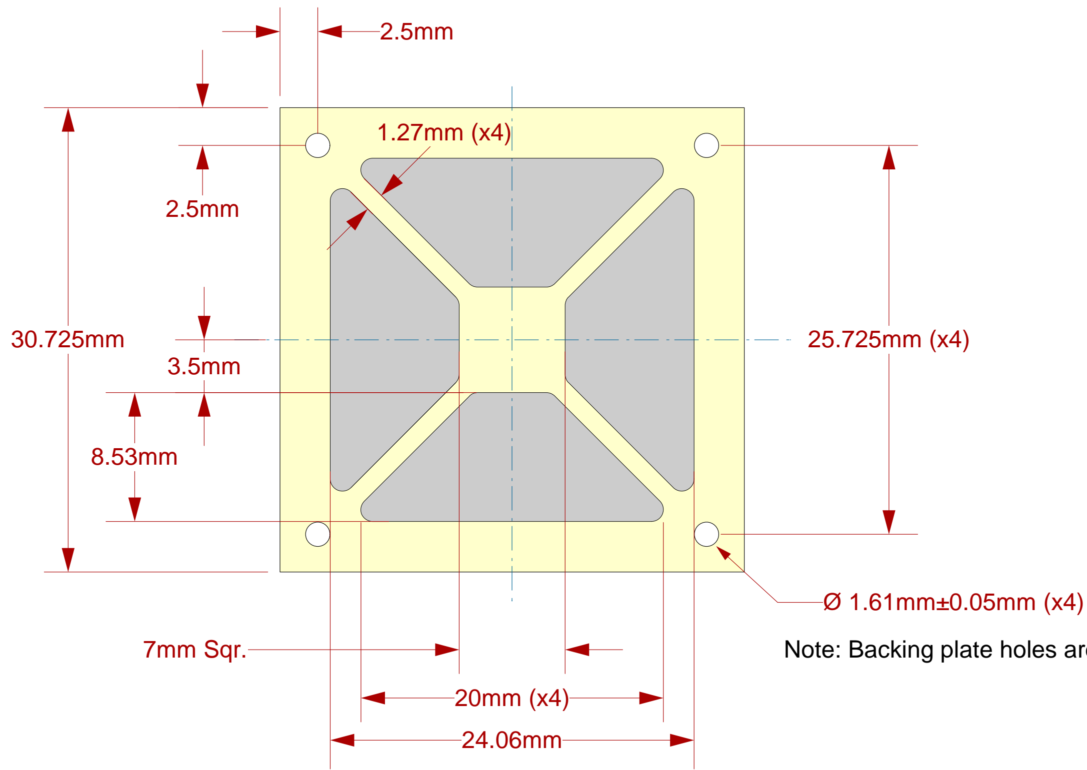
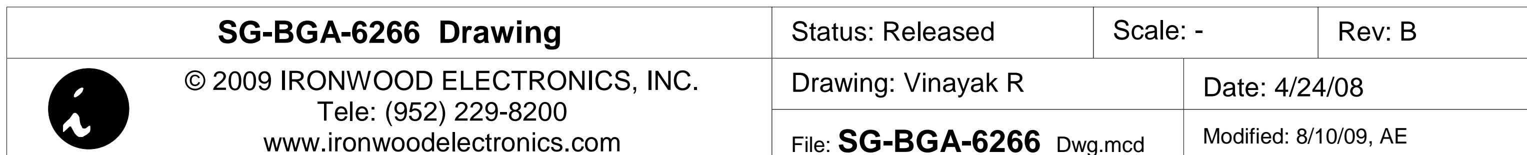
Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View

Description: Backing Plate with Insulation Plate



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